Peter Yau

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• Leading Independent Distributor of EE Components
• Bilingual in Chinese and English languages

As a project manager at hkorigin,.ltd, I lead a team of hardware and software engineers with rich electronics experience. I have expertise in designing and developing a wide range of embedded hardware & RF products in a variety of fields including commercial, ROS, 3D SLAM, consumer electronics, automotive and industrial applications. With a proven track record of delivering production-ready hardware, I excel at building robust, high-quality designs that balance cost efficiency and performance. My development process includes rapid prototyping, meticulous circuit design for digital, analog and mixed-signal designs, and comprehensive PCB design and firmware development. I am passionate about transforming concepts into reliable system-level solutions and am committed to delivering innovative hardware that meets stringent quality standards while optimizing manufacturing costs. Most importantly, with the latest PCB production process, we ensure high quality, low cost and fast production time up to 32 layers, and with global sourcing, vast inventory and EE expertise for over 20 years, we provide EE components with high quality, competitive price and fast delivery, so that we can turn customers' ideas into real products and provide customers with the best satisfaction, providing a complete and excellent integrated system.

PROFESSIONAL EXPERIENCE

CTO & Project Manager, HKOrigin,.Ltd, Shenzhen // *Oct 2023 – Present*
- As a development team leader for a full-stack engineering consulting firm providing custom hardware and embedded solutions for IoT products, smart devices, and industrial applications, I have successfully completed the development of over 70 products across a variety of industries.
- Led hardware design and development of the entire product while managing cross-functional collaboration with mechanical designers and manufacturing partners, ensuring seamless product integration and successful deployment.
- Worked with startups and established companies to deliver a wide range of embedded systems, wireless devices, medical electronics, wearable technology, and industrial IoT solutions, accelerating product validation, field trials, and investor demonstrations.

Project Manager, Bslet-Technology-Co-Ltd, Shenzhen // *Sep 2021 – Feb 2023*
- Design and develop the most efficient and technologically advanced engineering solutions for our customers by satisfying the end-user requirements and continuous customer feedback.
- Develop innovative products from scratch and oversee production chain as well.
- Explore and integrate AI technologies to enhance the functionality and performance of embedded systems..

Project Specialist, SKNT (Shenzhen Kingbird Network Technology Co., Ltd), Shenzhen // *Mar 2018 – Dec 2020*
- Design and development for embedded systems, focusing on GPS, AGPS systems, wireless technologies Wi-Fi, Bluetooth, RFID, LoRa and 4G/5G.
- Collaborating with cross-functional teams, including hardware, software, and system engineers, to ensure product performance, integration, and optimization.
- Responsible for troubleshooting, validating, and ensuring the scalability and reliability of the products in real-world applications.

RF & Embedded Systems Engineer, SHSTE (Shenzhen Haiyi Science and Technology Electronics Co., Ltd), Shenzhen // *Jan 2017 – Feb 2018*
- Responsible for designing and developing RF systems and embedded solutions, integrating hardware and software to optimize performance for wireless communication and radar applications.
- Engineered PCB board designs and conducted reviews to overcome issues with EMC/EMI, ESD, signal conditioning and Power isolation compliant to RF standards of ITU-R M, F series.

TECHNICAL SKILLS

- **Programming Languages:** C, C++, C#, VHDL/Verilog, Python, JavaScript
- **Embedded Technologies**
  - ✓ Microcontrollers: ARM Cortex-M, Esp32, AVR, PIC, MSP430, Renesas RX
  - ✓ SOCs: Raspberry Pi, Rockchip RK33, NXP, Jetson Nano/TX2, Xilinx Zynq UltraScale+, ESP32 SoC, FPGA, DSP, RTOS
  - ✓ Embedded AI: TensorFlow Lite, TinyML, NVIDIA Jetson
- **Hardware Design and Simulation**
  - ✓ PCB Design, Circuit Design, ROS, 3D SLAM, Radar System & Signal Processing Design, RF Design
  - ✓ Proteus, Ni Multisim, SPICE, MATLAB/SIM…, CST, ADS
- **Wireless Communication and IoT:**
  - ✓ Wi-Fi, BLE, 4/5G, ZigBee, Lora, RFID, ISM/SRD, GPS
  - ✓ IoT Protocols: MQTT, CoAP
- **AI Integration**
  - ✓ AI Frameworks: TensorFlow, Keras, OpenCV
  - ✓ AI machine vision: Smart Camera, Home Automation
- **Testing and Debugging**
- **Problem-Solving**
- **Version Control**
- **Project Leadership**
- **Collaboration and Teamwork**
- **Clear Communication**

EDUCATION

South China University of Technology (SCUT)
Master of Degree, Radio Engineering // *Mar 2014 - Oct 2016*

- Diligence in Embedded & RF Hardware Design and Software Development.

South China University of Technology (SCUT)
Bachelor of Degree, Electronics Engineering // *Apr 2009 - Sep 2013*

- Diligence in Digital/Analog/Mixed-signal Design.